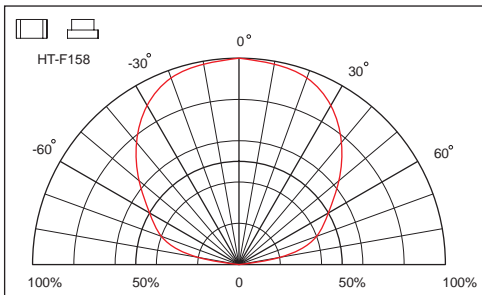
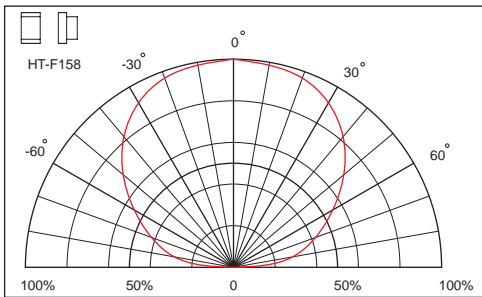


Characters

- Chip LED (3.2x1.6x1.2)
- Super compact type
- Lead frame type

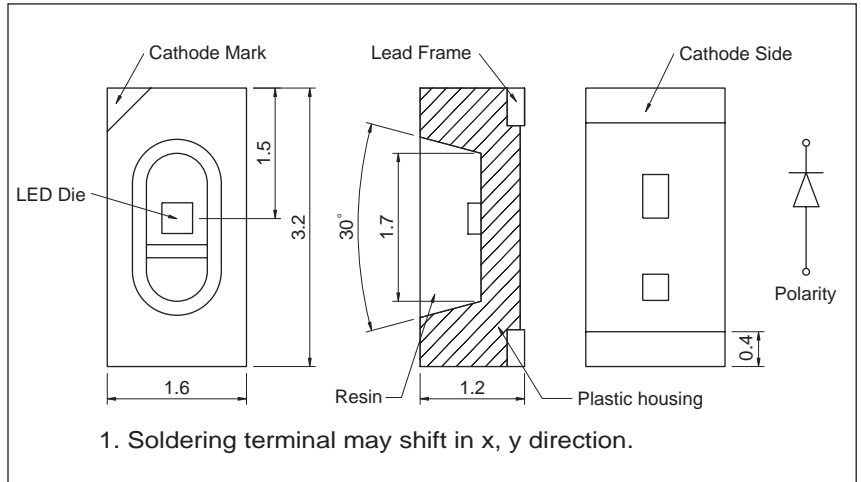


Directive Characteristics



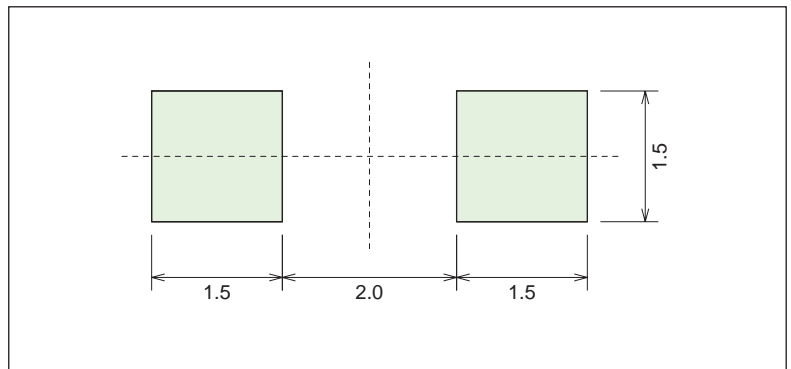
Package Outline Dimensions

(Unit:mm Tolerance:+/-0.15)



Recommended Soldering Pattern

Unit: mm



Absolute Maximum Ratings

(Ta=25 °C)

Item	Symbol	Value	Unit
		InGaN	
Power Dissipation	P _D	270	mW
DC Forward Current	I _F	60	mA
Pulsed Forward Current	I _{FP} *	200	mA
Reverse Voltage (I _R =100uA)	V _R	5	V
Operating Temperature	T _{OP}	-30 to 80	°C
Storage Temperature	T _{ST}	-40 to 85	°C

*Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width

Electrical-Optical Characteristics

(Ta=25 °C)

Code for parts	Lighting Color	Material	Forward Voltage (V)		Wavelength (nm) typ			Luminous Intensity (mcd)*		I _F (mA)
			typ	max	λ _D	λ _P	Δλ	min	typ	
HT-F158NB	Blue	InGaN	3.3	3.9	470	468	40	40	100	20
HT-F158NG	Green	InGaN	3.3	3.9	527	520	40	100	220	20
HT-F158NW	White	InGaN	3.3	3.9	X=0.29 Y=0.31	468	-	100	220	20

*Per NIST standards